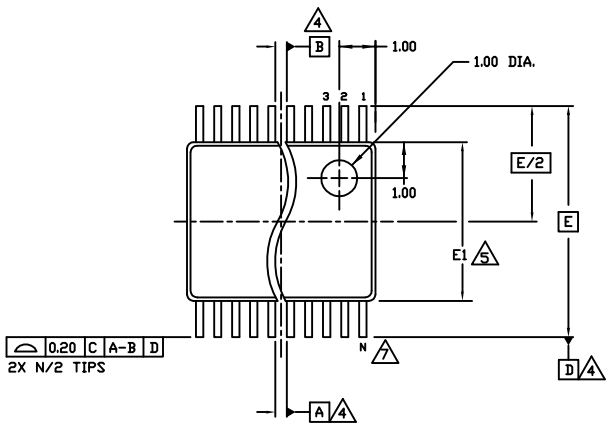
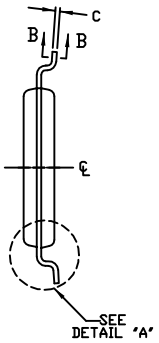
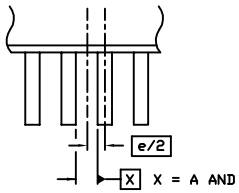
REVISION HISTORY				
REV	DESCRIPTION	DATE	ORIGINATED	INCORPORATED
00	INITIAL RELEASE PER DCN# D24480.	10/23 1996	D.T.R.	
01	RELEASED PER DCN #D24859	03/18 1997	D.T.R.	
02	REVISED PER DCN #D25490	02/27 1998	D.T.R.	
03	INCORPORATED PER DCN #P90321.	04/21 1999	L.S.E.	
04	REVISED PER DCN C17253 38118/A3 BECOMES 38118/04	07/19 2002	JDCAM	MCSAB



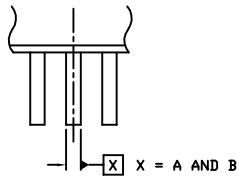
TOP VIEW



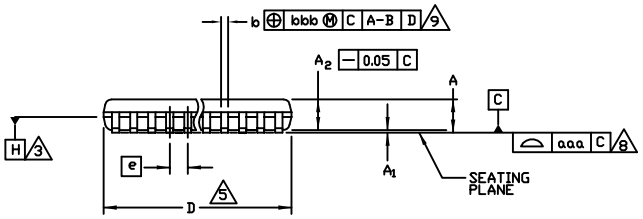
END VIEW



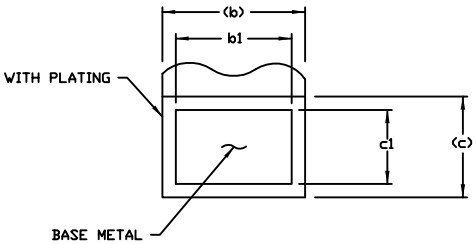
EVEN LEAD SIDES TOPVIEW



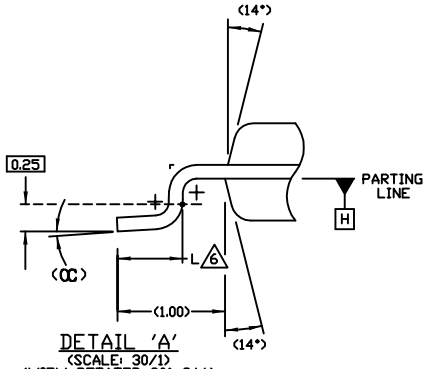
ODD LEAD SIDES TOPVIEW



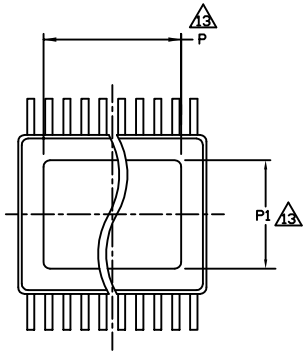
SIDE VIEW



SECTION "B-B"
SCALE: 120/1
(SEE NOTE 10)



DETAIL 'A'
(SCALE: 30/1)
(VIEW ROTATED 90° C.W.)



EXPOSED PAD VIEW

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS DECIMAL X.X ± X.XX ± X.XXX ± ANGULAR ± INTERPRET DIM AND TOL PER ASME Y14.5M – 1994 MATERIAL FINISH PRINTING IS SCALED TO FIT DO NOT SCALE DRAWING	THIRD ANGLE PROJECTION	Amkor Technology, Inc. Chandler, Arizona, USA Anam Semiconductor, Inc., Seoul, Korea Amkor Technology Philippines, Inc. Manila, Philippines	
	APPROVALS / DATE DRAWN P. BRIDGES 4/23 1997 CHECKED D. ROMAN 4/23 1997 APPROVED M. CARTER 4/23 1997 RELEASED YM KANG 10/23 1996	TITLE: PACKAGE OUTLINE, 4.40mm BODY, TSSOP/ePAD TSSOP, AAWW	
		SIZE A3 / DWG NUMBER 38118 / REV 04 SCALE 8/1 / CUSTOMER CODE / SHEET 1 OF 2	